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**UNITED STATES  
SECURITIES AND EXCHANGE COMMISSION**  
Washington, DC 20549

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**FORM 6-K**

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**REPORT OF FOREIGN PRIVATE ISSUER  
PURSUANT TO RULE 13a-16 OR 15d-16  
UNDER THE SECURITIES EXCHANGE ACT OF 1934**

**For the month of January, 2018**

**Commission File Number 001-37928**

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**ChipMOS TECHNOLOGIES INC.**  
(Translation of Registrant's Name Into English)

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**No. 1, R&D Rd. 1, Hsinchu Science Park  
Hsinchu, Taiwan  
Republic of China  
(Address of Principal Executive Offices)**

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(Indicate by check mark whether the registrant files or will file annual reports under cover of Form 20-F or Form 40-F.)

Form 20-F       Form 40-F

Indicate by check mark if the registrant is submitting the Form 6-K in paper as permitted by Regulation S-T Rule 101(b)(1):

Indicate by check mark if the registrant is submitting the Form 6-K in paper as permitted by Regulation S-T Rule 101(b)(7):

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**SIGNATURES**

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

ChipMOS TECHNOLOGIES INC.  
(Registrant)

Date: January 3, 2018

By /S/ S. J. Cheng  
Name: S. J. Cheng  
Title: Chairman & President

## Contacts:

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## **ChipMOS to Present at Credit Suisse's 2018 Greater China Technology and Internet Conference**

**Hsinchu, Taiwan - January 3, 2018** - ChipMOS TECHNOLOGIES INC. ("ChipMOS" or the "Company") (Taiwan Stock Exchange: 8150 and NASDAQ: IMOS), an industry leading provider of outsourced semiconductor assembly and test services ("OSAT"), today announced that it will present at Credit Suisse's 2018 Greater China Technology and Internet Conference, in Hong Kong on Wednesday, January 10 and Thursday, January 11, 2018.

Management from the Company, including Mr. S.J. Cheng, Chairman and President, Mr. David W. Wang, Vice President, Strategy and Investor Relations, and Mr. G.S. Shen, Deputy Director of Investor Relations, will host meetings with institutional investors to discuss the Company's financial performance, business trends and growth opportunities. There will be no webcast of the conference. The Company's investor update is currently available on the investor relations' section of its website at [www.chipmos.com](http://www.chipmos.com).

### **About ChipMOS TECHNOLOGIES INC.:**

ChipMOS TECHNOLOGIES INC. (Taiwan Stock Exchange: 8150 and NASDAQ: IMOS) (<http://www.chipmos.com>) is an industry leading provider of outsourced semiconductor assembly and test services. With advanced facilities in Hsinchu Science Park, Hsinchu Industrial Park and Southern Taiwan Science Park in Taiwan, ChipMOS provide assembly and test services to a broad range of customers, including leading fabless semiconductor companies, integrated device manufacturers and independent semiconductor foundries.

### **Forward-Looking Statements**

This press release may contain certain forward-looking statements. These forward-looking statements may be identified by words such as 'believes,' 'expects,' 'anticipates,' 'projects,' 'intends,' 'should,' 'seeks,' 'estimates,' 'future' or similar expressions or by discussion of, among other things, strategy, goals, plans or intentions. These statements may include financial projections and estimates and their underlying assumptions, statements regarding plans, objectives and expectations with respect to future operations, products and services, and statements regarding future performance. Actual results may differ materially in the future from those reflected in forward-looking statements contained in this document, due to various factors. Further information regarding these risks, uncertainties and other factors are included in the Company's most recent Annual Report on Form 20-F filed with the U.S. Securities and Exchange commission (the "SEC") and in the Company's other filings with the SEC.